

**AMENDMENTS TO THE SPECIFICATION:**

Please amend paragraph [0043] as follows:

The ceramic substrate 12 is preferably formed by sintering a low temperature co-fired ceramic (LTCC) material. The low temperature co-fired ceramic material is a ceramic material which can be sintered at a temperature of about 1050°C or less and can be co-sintered with a material having a low specific resistance, such as silver or copper. Examples of the low temperature co-fired ceramic material include glass composite LTCC materials which are a mixture of a borosilicate glass and a ceramic powder of alumina, forsterite, or other suitable materials; crystallized glass LTCC materials of ZnO-MgO-Al<sub>2</sub>O<sub>3</sub>-SiO<sub>2</sub> crystallized glasses; and glass-free LTCC materials of BaO-Al<sub>2</sub>O<sub>3</sub>-SiO<sub>2</sub> ceramic powder, Al<sub>2</sub>O<sub>3</sub>-CaO-SiO<sub>2</sub>-MgO-B<sub>2</sub>O<sub>3</sub> ceramic powder, or other suitable materials. The wiring patterns ~~12~~13 can be formed with metal having a low specific resistance and a low melting point, such as silver or copper, by forming the ceramic substrate ~~13~~12 with the low temperature co-fired ceramic material. Therefore, the ceramic substrate 12 and the wiring patterns 13 can be co-sintered at a low temperature of about 1050°C or less.